

# 2MBI300VE-120-50

**IGBT Modules** 

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# **IGBT MODULE (V series)** 1200V / 300A / 2 in one package

#### Features

High speed switching Voltage drive Low Inductance module structure

#### Applications

Inverter for Motor Drive AC and DC Servo Drive Amplifier Uninterruptible Power Supply Industrial machines, such as Welding machines

### Maximum Ratings and Characteristics

Absolute Maximum Ratings (at Tc=25°C unless otherwise specified)

tems	Symbols Conditions		Maximum ratings	Units		
Collector-Emitter voltage	VCES				V	
Gate-Emitter voltage	VGES			±20	V	
Collector current	Ic	Continuous	Tc=100°C	300		
			Tc=25°C	360		
	Ic pulse	1ms		600		
	-lc			300		
	-lc pulse	1ms	1ms			
Collector power dissipation	Pc	1 device	1 device		W	
lunction temperature	Tj			175		
Operating junction temperature (under switching conditions	) T <sub>jop</sub>			150	°C	
Case temperature	Tc			125		
Storage temperature	Tstg			-40 ~ +125		
solation voltage between terminal and copper base (*1)	Viso	AC : 1min.		2500	VAC	
Mounting (*2)				6.0	Nm	
Screw torque Terminals (*3)	-			5.0	Nm	

Note \*1: All terminals should be connected together during the test. Note \*2: Recommendable Value : 3.0-6.0 Nm (M5 or M6) Note \*3: Recommendable Value : 2.5-5.0 Nm (M6)

#### • Electrical characteristics (at Tj= 25°C unless otherwise specified)

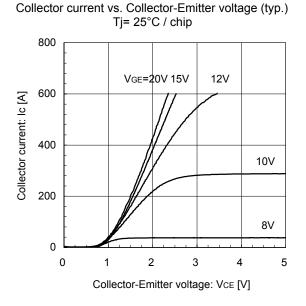
	Symbolo	Conditions	O su all'élana		Characteristics		
ems	Symbols	Conditions		min.	typ.	max.	Units
Zero gate voltage collector current	ICES	V <sub>GE</sub> = 0V, V <sub>CE</sub> = 1200V		-	-	2.0	mA
Gate-Emitter leakage current	IGES	$V_{CE} = 0V, V_{GE} = \pm 20V$		-	-	800	nA
Gate-Emitter threshold voltage	VGE (th)	V <sub>CE</sub> = 20V, I <sub>c</sub> = 300mA		6.0	6.5	7.0	V
Collector-Emitter saturation voltage	V		Tj=25°C	-	2.05	2.60	V
	V <sub>CE (sat)</sub>		Tj=125°C	-	2.40	-	
	(terminal)	V <sub>GE</sub> = 15V I <sub>c</sub> = 300A	Tj=150°C		2.45		
	V		Tj=25°C	-	1.85	2.15	
	V <sub>CE (sat)</sub>		Tj=125°C	-	2.20	-	
	(chip)		Tj=150°C		2.25		
Input capacitance	Cies	V <sub>CE</sub> = 10V, V <sub>GE</sub> = 0V, f = 1M	Ηz	-	24	-	nF
Input capacitance Turn-on time	ton	Vcc = 600V Ls = 30nH	-	0.60	-	μs	
	tr	Ic = 300A	-	0.20	-		
	tr (i)	$V_{GE} = \pm 15V$	-	0.05	-		
Turn-off time	toff	$R_{G} = 1.8\Omega$		-	0.80	-	1
	tf	Tj = 150°C	-	0.08	-	1	
Forward on voltage	VF	V <sub>GE</sub> = 0V I <sub>F</sub> = 300A	Tj=25°C	-	1.85	2.40	V
	(terminal)		Tj=125°C	-	2.00	-	
	(terminal)		Tj=150°C		1.95		
	VF		Tj=25°C	-	1.70	2.15	
			Tj=125°C	-	1.85	-	
	(chip)		Tj=150°C		1.80		
Reverse recovery time	trr	IF = 300A		-	0.15	-	μs

#### • Thermal resistance characteristics

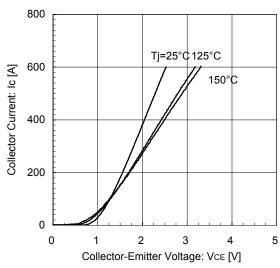
Items	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	Units
Thermal resistance (1device)	Rth(j-c)	IGBT	-	-	0.068	°C/W
		FWD	-	-	0.110	
Contact thermal resistance (1device) (*4)	Rth(c-f)	with Thermal Compound	-	0.0125	-	

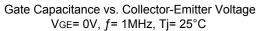
Note \*4: This is the value which is defined mounting on the additional cooling fin with thermal compound.

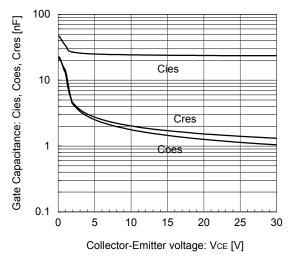
#### Characteristics (Representative)

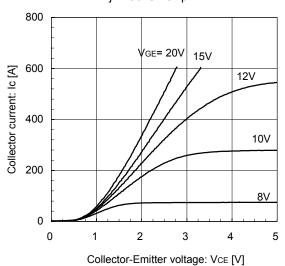


Collector current vs. Collector-Emitter voltage (typ.) VGE= 15V / chip

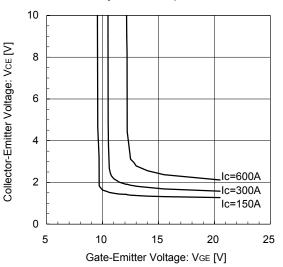




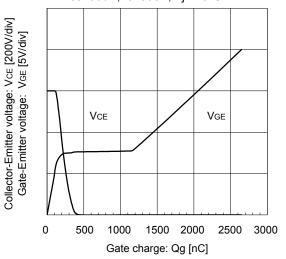




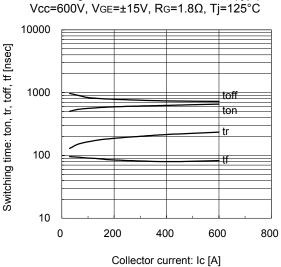
Collector-Emitter voltage vs. Gate-Emitter voltage Tj= 25°C / chip



Dynamic Gate Charge (typ.) Vcc=600V, Ic=300A, Tj= 25°C

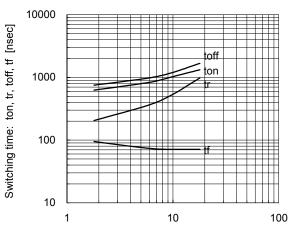


Collector current vs. Collector-Emitter voltage (typ.) Tj= 150°C / chip



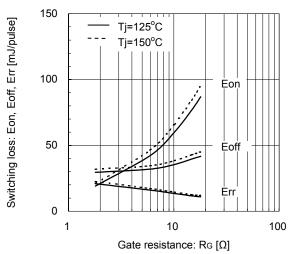
Switching time vs. Collector current (typ.)

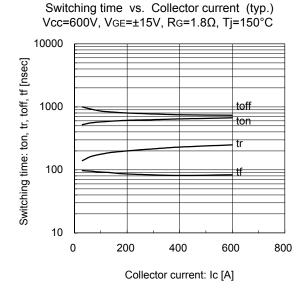
Switching time vs. Gate resistance (typ.) Vcc=600V, Ic=300A, Vge=±15V, Tj=125°C



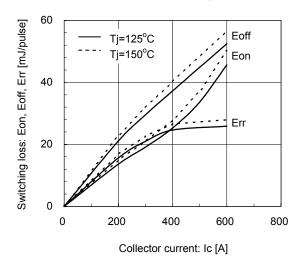
Gate resistance: Rg  $[\Omega]$ 

Switching loss vs. Gate resistance (typ.) Vcc=600V, Ic=300A, VGE=±15V, Tj=125°C, 150°C

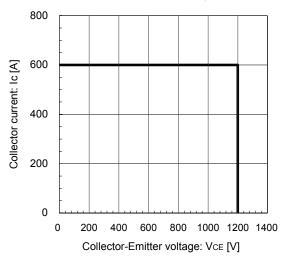


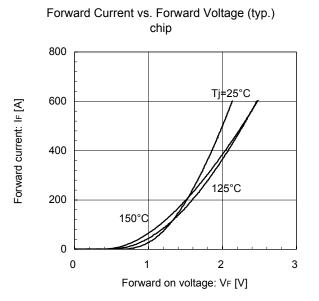


Switching loss vs. Collector current (typ.) Vcc=600V, VGE=±15V, RG=1.8Ω, Tj=125°C, 150°C

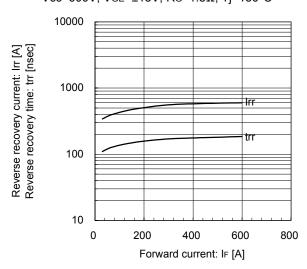


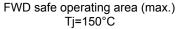
Reverse bias safe operating area (max.) +VGE=15V, -VGE=15V, RG=1.8Ω, Tj=150°C

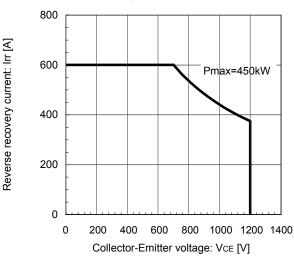


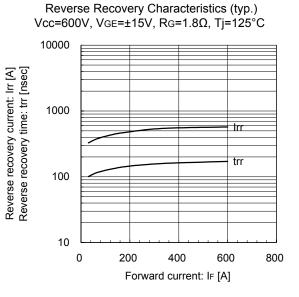


Reverse Recovery Characteristics (typ.) Vcc=600V, Vge=±15V, Rg=1.8Ω, Tj=150°C

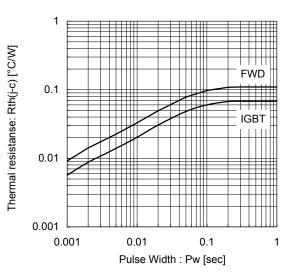






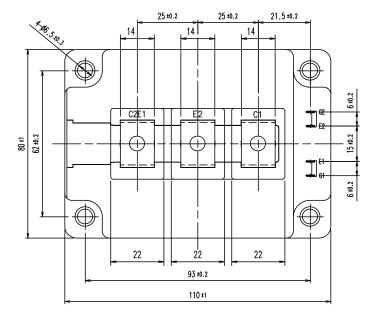


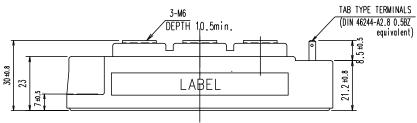
Transient Thermal Resistance (max.)



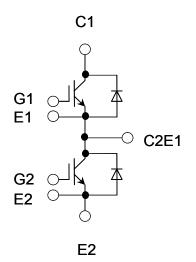
http://www.fujielectric.com/products/semiconductor/

## Outline Drawings, mm





Equivalent Circuit Schematic



http://www.fujielectric.com/products/semiconductor/

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